

CLAIMS:

1. (Currently Amended) An integrated circuit comprising:

a first bus;

a second bus;

a third bus;

a fourth bus;

a shunting circuit including a plurality of transistors in a stacked configuration, the shunting circuit having a plurality of control terminals, a first current terminal coupled to the first bus, and a second current terminal coupled to the second bus, and an intermediate terminal coupled to the fourth bus, wherein the shunting circuit is made conductive to provide a discharge path from the first bus to the second bus for current from an electrostatic discharge (ESD) event;

a trigger circuit having a first output coupled to a first control terminal of the plurality of control terminals of the shunting circuit to provide a first control signal and having a second output coupled to a second control terminal of the plurality of control terminals of the shunting circuit to provide a second control signal, the trigger circuit is coupled to the third bus; and

a pad, the pad coupled to the first bus, the second bus, and the third bus.

2. (Original) The integrated circuit of claim 1 further comprising:

a pull-up device, the pad coupled to the third bus via the pull-up device.

3. (Original) The integrated circuit of claim 2 wherein the pull-up device includes a diode.

4. (Original) The integrated circuit of claim 1 wherein during a detection of an ESD event, the first output and the second output are pulled to substantially a voltage of the third bus to make conductive the shunting circuit to discharge current of the ESD event from the first bus to the second bus.

5. (Original) The integrated circuit of claim 1 wherein the trigger circuit further comprises a first switch and a second switch, wherein during the detection of an ESD event, the first switch and the second switch are made conductive to provide a current path between the third bus and the first output and between the third bus and the second output.

6. (Currently Amended) The integrated circuit of claim 1 wherein during a normal operation of the integrated circuit, the first output is pulled substantially to a voltage of ~~a~~ the fourth bus, and the second output is pulled substantially to a voltage of the second bus, wherein the voltage of the fourth bus is different than the voltage of the second bus.

7. (Original) The integrated circuit of claim 6 wherein:

the plurality of transistors are of a process technology having an associated maximum voltage, the first output being pulled substantially to the voltage of the fourth bus and the second output being pulled substantially to the voltage of the second bus places the transistors of the plurality in a state such that a voltage drop across each transistor of the plurality is less than the maximum voltage.

8. (Currently Amended) The integrated circuit of claim 1 wherein during a normal operation of the integrated circuit, the first output is at a first voltage, and the second output is at a second voltage, the first voltage is different from the second voltage.

9. (Currently Amended) The integrated circuit of claim 1 wherein during a normal operation of the integrated circuit, the trigger circuit provides a current path between ~~a~~ the fourth bus and the first output and provides a second current path between the second bus and the second output.

10. (Currently Amended) The integrated circuit of claim 1 wherein:

the trigger circuit includes an internal node;  
during a normal operation, the internal node is pulled substantially to a voltage of ~~a~~ the fourth bus;  
during a normal operation, the fourth bus is at a power supply voltage; and

during an ESD event, the internal node is pulled substantially to a voltage of the third bus.

11. (Original) The integrated circuit of claim 10 wherein:

the trigger circuit includes a pull-up circuit, wherein the pull-up circuit includes a capacitive pull-up device and/or a conductive pull-up device, wherein the internal node is coupled to the third bus via the capacitive pull-up device and/or the conductive pull-up device during an ESD event.

12. (Original) The integrated circuit of claim 11 wherein the conductive pull-up device is controlled by an output of an RC circuit.

13. (Original) The integrated circuit of claim 10, wherein the trigger circuit includes a detection circuit coupled to the internal node, the detection circuit detects an ESD event via the internal node.

14. (Original) The integrated circuit of claim 1 wherein the trigger circuit includes a slew rate detection circuit for detecting an ESD event.

15. (Canceled)

16. (Original) The integrated circuit of claim 1 wherein the transistors of the plurality are MOSFETS.

17. (Original) The integrated circuit of claim 1 further comprising:

a second shunting circuit including a plurality of transistors in a stacked configuration, the second shunting circuit having a first current terminal coupled to the first bus and a second current terminal coupled to the second bus, wherein the second shunting circuit is made conductive to provide a discharge path from the first bus to the second bus for current from an ESD event;

wherein the first output is coupled to a first control terminal of the second shunting circuit to provide the first control signal and the second output is coupled to the second control terminal of the second shunting circuit to provide the second control signal.

18. (Currently Amended) The integrated circuit of claim 1 further comprising:

a ~~fourth~~ fifth bus, the first control terminal coupled to the first output via the ~~fourth~~ fifth bus; and

a ~~fifth~~ sixth bus, the second control terminal coupled to the second output via the ~~fifth~~ sixth bus.

19. (Original) The integrated circuit of claim 18 wherein:

the pad and the shunting circuit are located in an I/O cell;  
the I/O cell includes a diode;  
the pad is coupled to the third bus via the diode.

20. (Original) The integrated circuit of claim 18 wherein:

the shunting circuit is located in an I/O cell; and  
the trigger circuit is located outside of the I/O cell.

21. (Original) The integrated circuit of claim 18 further comprising:

a plurality of shunting circuits coupled to a single trigger circuit.

22. (Original) The integrated circuit of claim 1 further comprising:

a second pad, the second pad is coupled to the first bus, the second bus, and the third bus.

23. (Original) The integrated circuit of claim 1 wherein:

the integrated circuit operates at a first supply voltage,  
the pad is coupled to receive external signals at a second voltage, the second voltage  
being higher than the first voltage.

24. (Currently Amended) The integrated circuit of claim 1 further comprising:  
the trigger circuit is implemented with a plurality of transistors of a process technology  
having an associated maximum voltage, wherein during normal operation, the  
~~boost~~ third bus is at a higher voltage than the maximum voltage.

25. (Currently Amended) The integrated circuit of claim 1 wherein during an ESD event, the  
third bus is at a first voltage and is at a higher voltage than the first bus is at a second voltage, the  
first voltage being higher than the second voltage.

26. (Currently Amended) A trigger circuit for an ESD protection circuit, the trigger circuit  
comprising:

a detection circuit coupled to a ground bus and to an internal node, the detection circuit  
for detecting an ESD event;

an internal node, the detection circuit detecting an ESD event via the internal node; and  
a pull-up circuit coupled to the internal node, to a boosted voltage bus, and to a positive  
power supply voltage bus;

wherein during normal operation, the internal node is coupled to a first the positive power  
supply voltage bus; and

wherein during an ESD event, the internal node is coupled to a second the boosted  
voltage bus via a pull-up circuit, the boosted voltage bus being at a higher voltage  
than the positive power supply voltage bus during the ESD event.

27. (Currently Amended) The trigger circuit of claim 26 wherein during normal operation, the  
second boosted voltage bus is at a greater voltage than the first positive power supply voltage  
bus.

28. (Currently Amended) The trigger circuit of claim 27 wherein the pull-up circuit includes a  
capacitive pull-up device and/or a conductive pull-up device, wherein the internal node is  
coupled to the third boosted voltage bus via the capacitive pull-up device and/or the conductive  
pull-up device during an the ESD event.

29. (Currently Amended) The trigger circuit of claim 26 further comprising:

a first output; and

a second output;

wherein during an ESD event, the trigger circuit providing at the first output and the second output, a first the boosted voltage; and

wherein during normal operation, the trigger circuit providing a second the positive power supply voltage at the first output and a third voltage at while the second output is coupled to ground, the second voltage being different than the first voltage.

30. (Currently Amended) A method of operating an (electrostatic discharge) ESD circuit, the method comprising:

providing, in response to detecting an ESD event, a first control signal and a second control signal at a voltage substantially equal to a voltage of a first boosted voltage bus of an integrated circuit to a first control terminal and a second control terminal, respectively, of a shunting devicee circuit, wherein the first control signal and the second control signal being at the voltage makes conductive the shunting circuit to discharge current of the ESD event from a second an ESD bus to a third ground bus; and

providing, during a normal operation of an integrated circuit, the first control signal at a second positive power supply voltage and the second control signal at a third voltage ground, wherein the second voltage is less than third voltage voltage of the boosted voltage bus is higher than the positive power supply voltage during the ESD event.

31. (Currently Amended) The method of claim 30 wherein the second voltage and the third voltage are at voltage levels so as to minimize leakage current through the shunting circuit comprises first and second cascoded transistors coupled between the ESD bus and the ground bus.